# Correspondence to PB-free soldering





## Medium-size Lead-free N<sub>2</sub> Reflow Soldering Machine RF-810

The model RF-810 is a medium Reflow Soldering Machine corresponding to lead-free soldering and using IR and hot air convection, and nitrogen (N<sub>2</sub>) for the basic heating. While this is a medium table-top reflow machine, it a method with 8 zones, and the precise and stable temperature profile required for lead-free reflow soldering can be obtained. By use of IR and hot air and nitrogen (N<sub>2</sub>), the various requirements for lead-free soldering can be met sufficiently.

### Features

- This is a table-top reflow soldering machine with correspondence to nitrogen (N<sub>2</sub>). Circuit boards up to 300×300mm can be processed.
- Rapid heating is performed with a 8-zone guartz heater using IR and hot air and nitrogen (N<sub>2</sub>), and the desired temperature profile can be obtained.
- Precise temperature control (±0.3%) up to max. 350°C and stable temperature profiles can be obtained with a high-precision PID temperature controller.

### Specifications

- Heating section : 8 zones, W300mm×L2080mm×H30mm (at the inlet). Heater : Quartz tube heater, IR (wavelength: 2 to 10 µm). Upper part : 1,2,6,7,8zone: 1.4kW / 3,4,5zone: 1.0kW Lower part : 1,2,6,7,8zone: 1.0kW (3,4,5zone: none) Heating method : IR + Hot air convection system Temperature control: Max. 350°C ±0.3%, P.I.D. temperature controller. Temperature control for the atmosphere in the upper part of the furnace for each zone. Convevor : W 300 mm, SUS mesh belt. 90 to 1400 mm/min Conveyor direction:  $R \rightarrow L \text{ or } L \rightarrow R$  (at user's request)
- Digital speed controller Cooling
- : Forced cooling by a fan on the outlet side
- 220V 17.9kW, 50/60 Hz Power supply : Single phase • N<sub>2</sub> supply quantity : About 20 to 100l/min
- (Oxygen density: about 10,000 ppm). Safety devices : Leak/Over-current circuit breaker, Emergency stop switch, Alarm output (over/under temperature / heater disconnection) • External dimensions: (W)2730×(D)630×(H)820mm,
- Weight : about 380kg.

#### Applicable circuit boards

- Dimensions : 15mm×15mm to 300mm×300mm
- Board thickness : 0.125mm to 2mm
- : Max. 30mm Height

### Applications

- Reflow soldering of SMT circuit boards.
- · Lead-free reflow soldering.
- Drying of thermosetting adhesives and other heating work.

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 $\star$ Specifications subject to change without notice.